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### **Kyzen to Display Micronox MX2302 at SEMICON China 2007**

**NASHVILLE — March 7, 2007** — Kyzen Corporation, a world leading provider of environmentally responsible precision cleaning products for electronics and high-technology manufacturing operations, announces that it will showcase Micronox MX2302 in distributor WKK's booth E2-2316 at the upcoming SEMICON China 2007 exhibition and conference scheduled to take place March 21-23, 2007 at the Shanghai New International Expo Centre in Shanghai, China.

Micronox MX2302 is a semi-aqueous cleaning solvent for semiconductor and wafer-level packaging applications. It is a high-strength solvent blend designed for optimum effectiveness in removing all types of uncured paste and adhesive residues from semiconductor wafer bumps found in electronic components including flip chip, chip scale and microBGA packages while being both user- and environmentally-friendly. Easy to use, MX2302 is applied as received, followed by a water rinse for complete removal of all soil and cleaner residues.

Features and benefits of MX2302 include free rinsing in water, a high flash point and use in S-U-I or ultrasonics. Additionally, it removes reflowed pastes, uncured SMT adhesives and lead-free pastes, brightens solder, is effective on tacky fluxes as well as OA fluxes and conductive adhesives, and is multi-metal safe.

MICRONOX MX2302 is a combustible solvent solution with 1034.9 g/L VOC at 100 percent. It contains no CFCs or HAPs, and is non-corrosive. MX2302 is available commercially in one, five and 55 gallon containers.

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